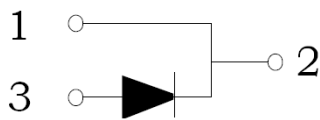


KF \$) - *

Ultrafast Recovery Diode in a TO-263 Plastic Package.

Silicon epitaxial process to produce ultrafast recovery diode with low reverse leakage current and high reliability.

For high frequency, high voltage, high current rectifier diode, freewheeling diode.



PIN1 Anode

PIN 2 4 Cathode

PIN 3 Anode

See Marking Instructions

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	600	V
RMS Voltage	V_{RMS}	420	V
DC Blocking Voltage	V_{DC}	600	V
Maximum Average Forward Current	I_F	1× 30	A
Peak forward surge current	I_{FSM}	300	A
Typical Thermal Resistance Junction to Case	$R_{\theta JC}$	2.0	/W
Junction Temperature Range	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

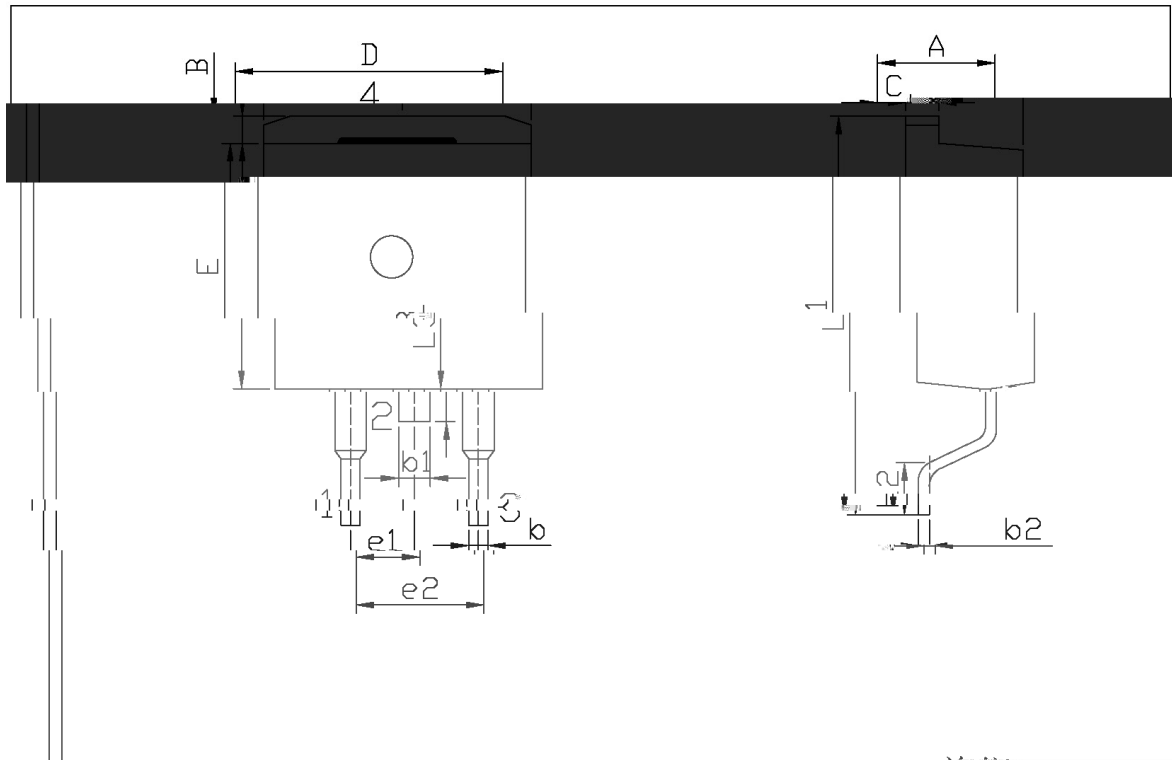
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	$I_F=5.0A$ $T_C=25$			1.35	V
		$I_F=5.0A$ $T_C=150$			1.15	
		$I_F=30A$ $T_C=25$			1.65	
		$I_F=30A$ $T_C=150$			1.25	
Instantaneous Reverse Current <small>Note1</small>	I_R	$V_R=600V$ $T_a=25$			0.25	mA
		$V_R=420V$ $T_a=150$			1	
		$V_R=600V$ $T_a=150$			2	
Reverse Recovery Time	t_{rr}	$I_F=0.5A$ $I_{RR}=0.25A$ $I_R=1.0A$			50	ns

&Notes

1. &Short duration pulse test used to minimize self-heating effect.
2. &Unless otherwise noted, values for the parameters of a single chip

IF - TC





单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeter	
	Min	Max		Min	Max
A	4.30	4.70	E	9.00	9.40
B	1.00	1.40	e1	2.34	2.74

